	Type	Hits	Search Text	DBs
1	BRS	634144	redistribut$ or interposer or interconnect$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
2	BRS	77612	(redistribut$ or interposer or interconnect$) and semiconduct$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
3	BRS	18106	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
4	BRS	6	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj post	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
5	BRS	6092	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
6	BRS	2684	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) and (mark or code or alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
7	BRS	465	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post) and (mark or code or alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
8	BRS	106	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post) and ((mark or code or alignment) with (pad or (Cu or copper)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB

	Type	Hits	Search Text	DBs
9	BRS	15	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post) and ((mark or code) with (pad or (Cu or copper)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
10	BRS	7	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post) and ((mark or code) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
11	BRS	9	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper) adj (layer or film or post) and ((mark or code) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
12	BRS	159	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) adj (layer or film or post) and ((mark or code) with (pad or metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
13	BRS	68	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) adj (layer or film or post) and ((mark or code) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
14	BRS	1264	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) adj (layer or film or post) and (mark or code)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
15	BRS	296	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper) adj (layer or film or post) and (mark or code)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB

	Type	Hits	Search Text	DBs
16	BRS	283	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper) adj (layer or film or post) and (mark or code)	USPAT; JPO
17	BRS	0	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) adj (layer or film or post) and (mark or code) adj member	USPAT
18	BRS	1	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) adj (layer or film or post) and (mark$ or code$) adj pad	USPAT
19	BRS	12	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) and (mark$ or code$) adj pad	USPAT
20	BRS	30	(redistribut$ or interposer or interconnect$) and (mark$ or code$) adj pad	USPAT; JPO
21	BRS	761	(redistribut$ or interposer or interconnect$) and (mark$ or code$) adj (pad or connect$)	USPAT; JPO
22	BRS	118	(redistribut$ or interposer or interconnect$) and (mark$ or code$) adj (pad or connect$) and semiconduct$	USPAT; JPO
23	BRS	0	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post) and ((mark or code) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB

	Type	Hits	Search Text	DBs
24	BRS	4	(redistribut$ or interposer or interconnect$) and semiconduct$ and (("mark" or code) adj (pad or "Cu" or copper))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
25	BRS	4553	(redistribut$ or interposer or interconnect$) and semiconduct$ and (probe$ or (("mark" or code) adj (pad or "Cu" or copper)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
26	BRS	9	(redistribut$ or interposer or interconnect$) and semiconduct$ and ((("mark" or code) adj (pad or "Cu" or copper or post or probe$)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
27	BRS	39	4769523.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
28	BRS	0	(redistribut$ or interposer or interconnect$) and semiconduct$ and ("mark on pad" or "code on pad")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
29	BRS	0	(redistribut$ or interposer or interconnect$) and ("mark on pad" or "code on pad")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
30	BRS	0	("mark on pad" or "code on pad")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
31	BRS	11	(redistribut$ or interposer or interconnect$) and semiconduct$ and ("mark" or "code") near pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
32	BRS	22	(redistribut$ or interposer or interconnect$) and (chip or wafer) and ("mark" or "code") near pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
33	BRS	0	("mark over pad" or "code over pad")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB

	Type	Hits	Search Text	DBs
34	BRS	0	("marking over pad" or "coding over pad")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
35	BRS	786	("mark" or code) adj member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
36	BRS	29	4681656.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
37	BRS	1082	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
38	BRS	540	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
39	BRS	543	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post or probe) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
40	BRS	96	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj (layer or film or post or probe) and wafer and mark	USPAT; JPO
41	BRS	6	(redistribut$ or interposer or interconnect$) and semiconduct$ and pad and (Cu or copper) adj post	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB

	Type	Hits	Search Text	DBs
42	BRS	8	((redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) adj (layer or film or post) and ((mark or code) with (pad or metal))) and (4681656.pn. or 4769523.pn. or 5657394.pn. or 5360988.pn. or 5192716.pn. or 6251694.pn. or 5952247.pn. or 5897371.pn. or 5821549.pn. or 5594273.pn. or 5393696.pn.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
43	BRS	11	4681656.pn. or 4769523.pn. or 5657394.pn. or 5360988.pn. or 5192716.pn. or 6251694.pn. or 5952247.pn. or 5897371.pn. or 5821549.pn. or 5594273.pn. or 5393696.pn.	USPAT; JPO
44	BRS	0	(redistribut$ or interposer or interconnect$) and pad and (Cu or copper or metal) adj (layer or film or post) and (mark$ or code$) adj member	USPAT
45	BRS	0	(redistribut$ or interpos$) and pad and (Cu or copper or metal) adj (layer or film or post or probe) and (mark$ or code$) adj member	USPAT
46	BRS	5	(redistribut$ or interpos$) and pad and (Cu or copper or metal) adj (layer or film or post or probe) and (mark$ or code$) adj (member or post or probe or layer)	USPAT

	Type	Hits	Search Text	DBs
47	BRS	1923	(interpos$) and pad and (Cu or copper or metal) adj (layer or film or post or probe)	USPAT
48	BRS	970	(interpos$) and pad and (Cu or copper or metal) adj (layer or film or post or probe) and electrode	USPAT
49	BRS	256	(interpos$) and pad and (Cu or copper or metal) adj (layer or film or post or probe) and electrode and ground	USPAT
50	BRS	258	(interpos$) and pad and (Cu or copper or metal) adj (layer or film or post or probe) and electrode and ground	USPAT
51	BRS	4	5565988.pn. or 5897193.pn. or 5844317.pn. or 5477067.pn.	USPAT
52	BRS	3	5955764.pn. or 5950070.pn. or 5897193.pn.	USPAT
53	BRS	0	(interpos$) and pad and (Cu or copper or metal) adj (probe) and electrode and ground	USPAT
54	BRS	3	(interpos$) and pad and (Cu or copper or metal) adj (post) and electrode and ground	USPAT
55	BRS	1	(redistrib$) adj layer and pad and (Cu or copper or metal) adj (post)	USPAT
56	BRS	1	(redistrib$) adj layer and pad and (Cu or copper or metal) adj (post or probe)	USPAT
57	BRS	11	(redistrib$) adj layer and pad and (Cu or copper or metal) adj (post or probe or layer)	USPAT
58	BRS	41	(redistrib$ or interpos$) adj layer and pad and (Cu or copper or metal) adj (post or probe or layer)	USPAT

	Type	Hits	Search Text	DBs
59	BRS	83	(redistrib$ or interpos$) adj layer and pad and (Cu or copper or metal) adj (post or probe or layer)	USPAT
60	BRS	24	(redistrib$ or interpos$) adj layer and pad and (Cu or copper) adj (post or probe or layer)	USPAT
61	BRS	24	(redistrib$ or interpos$) adj layer and pad and (Cu or copper) adj (post or probe or layer)	USPAT; JPO
62	BRS	28	5187020.uref.	USPAT
63	BRS	11690	(interpos$) and pad and (Cu or copper or metal)	USPAT
64	BRS	3	(interpos$) and pad near (Cu or copper or metal) adj post	USPAT
65	BRS	500	(interpos$) and pad near (Cu or copper or metal)	USPAT
66	BRS	11	(interpos$) and pad near (Cu or copper or metal) adj bump	USPAT
67	BRS	126	(interpos$) and pad and (Cu or copper or metal) adj bump	USPAT
68	BRS	0	vacuum adj chuck adj table and (suction or vacuum) adj groov$	USPAT
69	BRS	8	vacuum adj chuck adj table	USPAT
70	BRS	12	(vacuum or suction) adj chuck adj table	USPAT